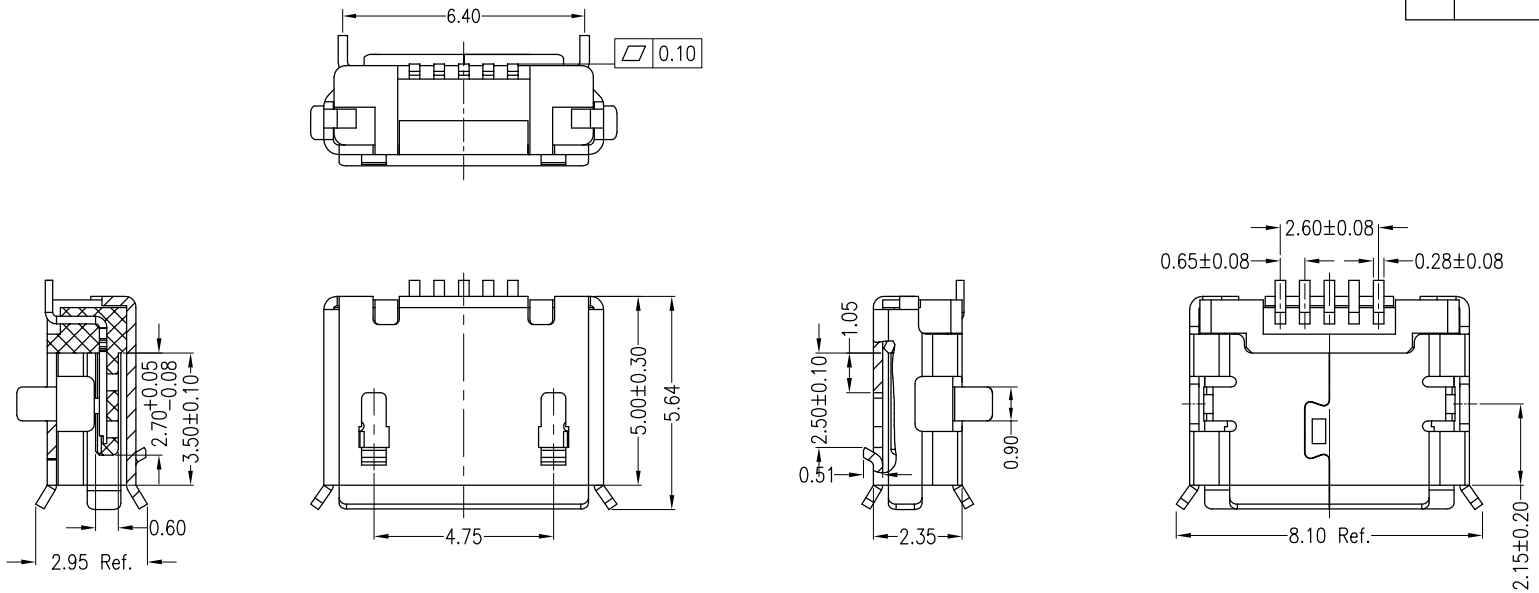
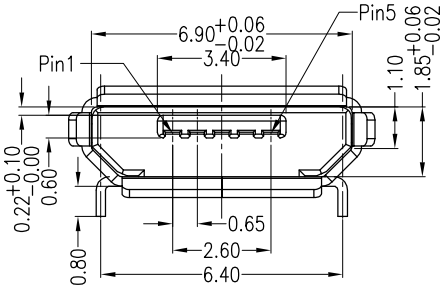
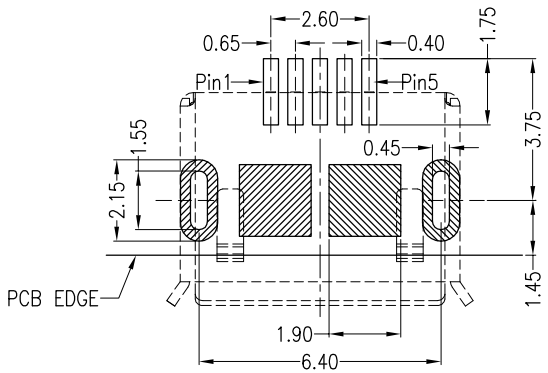
| REV. | ECN NO | LOCATIONS | DESCRIPTION | DATE |
|---|---|---|---|---|
| | | | | |




RECOMMANDED PCB LAYOUT

PCB图仅供参考

Note:

1.Material:

1.1 Housing: High temperature thermoplastic with g.f,UL94v-0

1.2 Contact: copper alloy,t=0.20mm

1.3 Shell: copper alloy,t=0.25mm

2.Specification:

2.1 Current rating:1,5PIN 1.8A Max/2,3,4PIN 1A Max.

2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.

2.3 Contact resistance: 30 mΩ Max.

2.4 Insulation resistance: 100 MΩ Min.

2.5 Total mating force: 3.57 Kgf Max.

2.6 Total unmating force: 1.0 Kgf Min.

2.7 Temperature range: -30°C~80°C

外壳材质

1:C268OR-H

外壳电镀

1:N50u''

2:雾T50u''

3:N+Au1u'' (脚)

4:Au1u''

端子电镀 01:Au1u'';02:Au1.5u'';03:Au3u''

05:Au5u'' ;10:Au10u'';15:Au15u'';30:Au30u''

主体颜色 B:黑色

主体材质 1:LCP

端子材质 4:C5191R-EH

| | | | |
|---|---|---|---|
| PART NO: USB-F06505-SC015 | | MATERAL: SEE NOTE | 深圳市旺富达电子有限公司 WFDCONN SHEN ZHEN WFD ELECTRONICS CO., LTD |
| MODEL NO: XX | | FINSH: SEE NOTE | |
| UNIT: MM | SIZE: A4 | COLOR: SEE NOTE | TITLE: Micro usb 5s B Type(插板6.4)无柱锡脚加长0.4 |
| TOLERANCE UNSPECIFIED .x 0.15 .xx 0.10 .xxx 0.05 Ang. 1° | | DR: LIU MIAO | DWG NO: A130 REV: A |
| | | CHK: SIMON | |
| | | APP: DAVID | SCALE: 5:1 DATE: 2012.05.17 |